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Supporting Information

Intrinsic toughened conductive thermosetting epoxy resins: utilizing dynamic bond and electrical conductivity to access electric and thermal dual-driven shape memory

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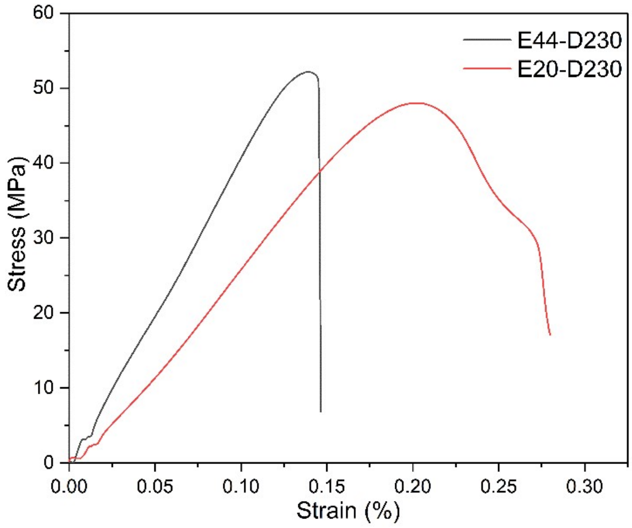

Figure S1 The Tensile stress–strain curves of original epoxy resin matrix.

Video S1 The process of Electro-induced shape memory